Moldex3D

Moldex3D Technology Summit and User's conference 2011

 » Date : October 3-4, 2011
» Venue: Sheraton Hotels & Resorts 21111 Haggerty Road. Novi. Michigan 48375. USA +1 - 248 - 349-4000





Moldex3D is delighted to announce the date for 2011 technology summit and users conference will be held in Novi, Michigan, USA. Make sure you' ve preserved your schedule on Oct 2-4. This year's content is provided in collaboration with Moldex3D customer' presentation, industry professionals and three key developers/founders of Moldex3D. Register for Moldex3D event today!

The agenda features the following highlights:

Moldex3D Users Presentations

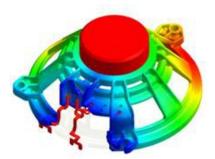
Academic and Industry Experts' Speeches

R11 Product Announcement

- Your key competence Cloud Computing in Moldex3D
- More realistic simulation Structural CAE Integrations
- Cooling matters productivity- Variotherm and Conformal Cooling
- Diversified Application Alternative molding processes support
- Design plastics better Moldex3D for CAD/Designers

In-depth development Topics

- Long Fiber Reinforcement
- MuCell Technology
- Hot Runner Thermal Modeling





Event Contact : Tiffani Lin Moldex3D North America Sales & Support Center 21800 Haggerty Road, Suite 109 Northville, MI, 48167 Tel:+1-248-946-4570 ext.101 support.us@moldex3d.com

Past Attendees







Moldex3D Moldex3D Technology Summit and User's conference 2011



Monday, October 3, 2011

Time	Presentation Topic	Presenter
08:00 - 09:00	Continental Breakfast and Reception	
09:00 - 09:40	Software Capability Enhancement Illustrations:Parallel and Cloud Computing Key Insights about Customer Success Stories	Dr. Venny Yang President / Moldex3D
09:40 - 10:30	What's New in Moldex3D R11 Moldex3D Future Roadmap of Software Development	Dr. David Hsu VP R&D / Moldex3D
10:30 - 11:00	Break and Partner Exhibition	
11:00 - 11:40	In-depth Discussion on Long Fiber Reinforcement, Mucell, Hot Runner Thermal Modeling, and IC-Packaging	Dr. Anthony Yang Chief Technology Officer / Moldex3D
11:40 - 12:10	Verifying and Improving the Plastics Deformation of Automotive Interior Parts at Early Design Stage	Jeff Webb CAE Manager / Ford Motor
12:10 - 13:30	Lunch	
13:30 - 14:15	Application of Multiple Criteria Optimization via Simulation to Injection Molding	Prof. Jose Castro Ohio State University
14:15 - 14:40	Interpreting Moldex3D Results	Kenneth Field CAE Engineer / Field Mold Solution
14:40 - 15:10	Break and Partner Exhibition	
15:10 - 15:35	Whirlpool Filter: 4 Gate Configuration versus 7 Gate Configuration	Charles Webster Product Development Engineer Hoffer Plastics
15:35 - 16:00	Product and Process Optimization Using Moldex3D Simulation	Vaibhav Mahajan Materials Development Engineer Hellermann Tyton
16:00 - 16:15	Sponsor's Presentation	Simulia
16:15 - 16:30	Questionnaire, First day wrap-up and Lucky draw	
16:30 - 17:30	Cocktail Reception and Networking	
Tuesday, Octo	ber 4, 2011	
Time	Presentation Topic	Presenter
08:00 - 09:00	Continental Breakfast and Reception	Jeff Kloberdanz
09:00 - 09:50	CAD-Integrated Analysis and Cloud Computing Demo	Application Engineer/Moldex3D Jim Davis PreSales Solutions Consultant/Siemens PLM Software
09:50 - 10:30	Recent Developments in Microcellular Injection Molding	Prof. Lih-Sheng (Tom) Turng University of Wisconsin
10:30 - 10:50	Break and Partner Exhibition	
10:50 - 11:15	Effect of eDesign Meshing Control on Molding Simulation	Dr. Linhuo Shi CAE Manager / Toyoda Gosei
11:15 - 11:30	Sponsor's Presentation	ETA

Understanding Shear Induced Melt Imbalances & MeltFlipper 11:30 - 12:00 Technology 12:00 - 13:00 Lunch (End of Exhibit 13:30) How to Get Closer to Reality: Practical Verification Study of 13:00 - 13:25 Moldex3D by Different Process Settings with a Molded Water Meter Part 13:25 - 13:50 **Runner and Gate Verification** 13:50 - 14:15 **Design and Process Improvement Case Studies** 14:15 - 14:40 **Users Forum**

Beaumont Technologies Raj Manickam Sr.

Dr. John Beaumont

President and CEO

CAE Engineer Mueller System Wade Von Linsowe Mold Engineer Extreme tooling Natalia Hilbert

Molding/Tooling Engineer Gecom

Moldex3D Executive team

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Open Q&A and Lucky draw

Cocktail Reception and Networking

Past Attendees

14:40 - 15:00

15:00 - 16:00

Bosch, BASF, Cimatron, DSM, Ford, Foxconn, GM, Henkel, Hynix, Lego, LG, Molex, Olympus, Panasonic, Samsung, Ticona, Toyota, Unilever, Visteon, etc…